



Material Content Data Sheet



Sales Product Name		BSD316SN H6327		Issued		29. August 2013		
MA#		MA000974354						
Package		PG-SOT363-6-6		Weight*		6.66 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.002	0.03		311	
	noble metal	gold	7440-57-5	0.008	0.12		1204	
	inorganic material	silicon	7440-21-3	0.122	1.84	1.99	18367	19882
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		99	
	non noble metal	titanium	7440-32-6	0.003	0.05		494	
	non noble metal	chromium	7440-47-3	0.010	0.15		1482	
	non noble metal	copper	7440-50-8	3.275	49.16	49.37	491802	493877
wire	non noble metal	copper	7440-50-8	0.050	0.76	0.76	7568	7568
encapsulation	organic material	carbon black	1333-86-4	0.029	0.44		4352	
	plastics	epoxy resin	-	0.623	9.36		93563	
	inorganic material	silicondioxide	60676-86-0	2.246	33.73	43.53	337262	435177
leadfinish	non noble metal	tin	7440-31-5	0.213	3.20	3.20	32016	32016
plating	noble metal	silver	7440-22-4	0.076	1.15	1.15	11480	11480
*deviation	< 10%		Sum in total:			100,00		1000000

Important Remarks:

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